

What is claimed is:

1. A semiconductor device comprising:
 - an adhesive layer on a substrate;
 - an insulating film on said adhesive layer; and
 - 5 light emitting elements on said insulating film,
wherein emitted from said light emitting elements is emitted through said substrate.

2. A device according to claim 1, wherein said substrate is a plastic substrate

10 comprising an organic material.

3. A device according to claim 1, wherein said semiconductor device further comprises driver circuits on said insulating film, and said light emitting elements and said driver circuits comprise TFTs.

15 4. A device according to claim 1, wherein color filters are provided on said substrate at positions aligned with said light emitting elements.

5. A device according to claim 4, wherein said insulating film covers said color
20 filters, and is planarized.

6. A device according to claim 4, wherein red color filters of said color filters are provided at positions aligned with at least the channel forming regions of said TFTs.

25 7. A device according to claim 1, wherein said adhesive layer comprises a

material selected from the group consisting of polyimide, acrylic, and epoxy resin.

8. A device according to claim 1, wherein a fixing substrate is provided over said light emitting element so as to face said substrate.

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9. A device according to claim 4, further comprising a black mask together with said color filters.

10. A device according to claim 1, wherein said semiconductor device is selected
from the group consisting of a video camera, a digital camera, a goggle type display,
a car navigation system, a personal computer, and a personal digital assistant.

11. A semiconductor device comprising:

a first substrate comprising an organic material and having TFTs provided

15 thereon;

a second substrate; and

a liquid crystal material retained between said first and second substrates,
wherein color filters are provided between said first substrate and said

TFTs.

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12. A device according to claim 11, wherein said first substrate comprising an organic material is a plastic substrate.

13. A device according to claim 11, further comprising an insulating film covering
25 said color filters and planarized.

14. A device according to claim 11, wherein said color filters are provided at positions aligned with at least the channel forming regions of said TFTs.

15. A device according to claim 11, further comprising a black mask together with
5 said color filters.

16. A device according to claim 11, wherein said semiconductor device is selected from the group consisting of a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, and a personal digital assistant.

10 17. A semiconductor device comprising:

color filters are provided on a substrate;

an adhesive layer over said substrate and said color filters;

an insulating film on said adhesive layer; and

15 light emitting elements on said insulating film,

wherein emitted from said light emitting elements is emitted through said substrate, and

20 wherein said substrate is a plastic substrate comprising an organic material.

18. A device according to claim 17, wherein said semiconductor device further comprises driver circuits on said insulating film, and said light emitting elements and said driver circuits comprise TFTs.

25 19. A device according to claim 17, wherein at positions aligned with said light

emitting elements.

20. A device according to claim 17, wherein red color filters of said color filters are provided at positions aligned with at least the channel forming regions of said
5 TFTs.

21. A device according to claim 17, wherein said adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.

10 22. A device according to claim 17, wherein a fixing substrate is provided over said light emitting element so as to face said substrate.

15 23. A device according to claim 17, further comprising a black mask together with said color filters.

24. A device according to claim 17, wherein said semiconductor device is selected from the group consisting of a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, and a personal digital assistant.

20 25. A method of manufacturing a semiconductor device comprising the steps of:

forming a separating layer on a first substrate;

forming an insulating film on said separating layer;

forming light emitting elements on said insulating film;

25 attaching a fixing substrate on said light emitting elements using a first

adhesive layer;

removing said separating layer by exposing said separating layer to gas containing halogen fluoride to separate said first substrate; and

attaching a second substrate to said insulating film using a second adhesive
5 layer,

wherein said second substrate has color filters provided thereon.

26. A method according to claim 25, wherein said first adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.

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27. A method according to claim 25, wherein said second adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.

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28. A method according to claim 25, wherein said second substrate is a plastic substrate.

29. A method according to claim 25, wherein said separating layer is a film comprising silicon.

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30. A method of manufacturing a semiconductor device comprising the steps of:

forming a separating layer on a first substrate;

forming an insulating film on said separating layer;

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forming an active layer, a gate insulating film, and gate electrodes on said

insulating film;

forming a first interlayer insulating film so as to cover said gate electrodes;

5 forming wiring and pixel electrodes on said first interlayer insulating film;

attaching a fixing substrate provided with an opposing electrode on said first substrate using a sealant;

injecting liquid crystal between said pixel electrodes and said opposing electrode;

10 removing said separating layer by exposing said separating layer to gas containing halogen fluoride to separate said first substrate; and

attaching a second substrate to said insulating film using an adhesive layer,

wherein said second substrate has color filters provided thereon.

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31. A method according to claim 30, wherein said adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.

20 32. A method according to claim 30, wherein said color filters are aligned with said active layer seen from the side of said second substrate.

33. A method according to claim 30, wherein said color filters are aligned with said active layer are red color filters.

25 34. A method according to claim 30, wherein said second substrate is a plastic

substrate.

35. A method according to claim 30, wherein said fixing substrate is a light transmitting substrate.

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36. A method according to claim 30, wherein said separating layer is a film comprising silicon.

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